EIE

EIE Enterprise (M) Sdn. Bhd. (944691-T)

HI-GRADE 3592-35 NO RESIDUE LEAD FREE FLUX

DESCRIPTION

HI-GRADE 3592-35 is a non-halide, no residue flux specifically developed for wave soldering, mixed technology and through hole electronic assemblies. This formulation provides greater heat stability required for the increased temperatures uses in lead free wave soldering processes.

HI-GRADE 3592-35 is formulated to provide a wide process window with excellent solderability, superior hole fill, and reduced solder balls on all surface finishes. This product can be used with Tin/Copper, Tin/Silver/Copper, and Tin/Lead alloys.

PROCESS RECOMMENDATIONS

HI-GRADE 3592-35 should be applied by spray for best results. Topside board temperatures for most circuit board assemblies can range from 240-300° F (115-149° C) depending on equipment, and board complexity. This product can be used in single and dual wave configurations. Typical conveyor speed is 4-6 ft/min.

The HI-GRADE 3592-35 should not require thinning when used in a closed spray fluxer system. If thinning is required use HI-GRADE 16-3000 flux thinner.

BENEFITS

- USE WITH LEAD FREE AND TIN/LEAD ALLOYS
- IPC FLUX ALLOYS
- EXCELLENT SOLDERABILITY ON ALL BOARD FINISHES
- SUPERIOR HOLE FILL
- REDUCES SOLDER BALLS

PHYSICAL PROPERTIES

	3592-35
Color	Clear
Specific Gravity	
@77° F(25° C)	0.828
@60° F(15° C)	0.833
Acid Value	35
Solids Content	4.5
Flash Point	54° F

IPC SURFACE INSULATION RESISTANCE

Test Pattern	Board	24 Hours	96 Hours	168 Hours
IPC B24	Control	4.04 X 10	4.69 X 10	4.78 X 10
	Pattern up	3.55 X 10	3.37 X 10	3.42 X 10
	Pattern down	1.24 X 10	1.54 X 10	1.51 X 10

All readings expressed in ohms

SAFETY

All fluxes with low flash points should be handled with caution. Store in a well ventilated area away from sparks, flames, and direct heat. Consult material safety data sheet for full details.

PACKAGING

25 /kg , 209 /kg Drum